

# Hiner-pack® MHWJ Canister 200 mm

*Engineered for safe handling of delicate wafers during shipping and storage*

Wafer jars provide an economical and reliable multi-wafer storage and transport solution, ideal for non-sensitive wafers in semiconductor production. Made from durable natural polypropylene, each jar is equipped with a secure-fitting lid to prevent accidental opening. Inside, a layered protection system—including interleaf separators, foam cushion disks, and liner foam walls—shields wafers from vibration, shock, and surface contact. Available in 150mm and 200mm sizes (custom sizes available), and offered in clear, white, or black for inspection or ESD control. Their stackable design optimizes cleanroom space, while the reusable construction reduces packaging waste. Perfect for in-fab storage and inter-fab wafer shipping, these jars ensure contamination prevention and physical protection for high-value wafers.



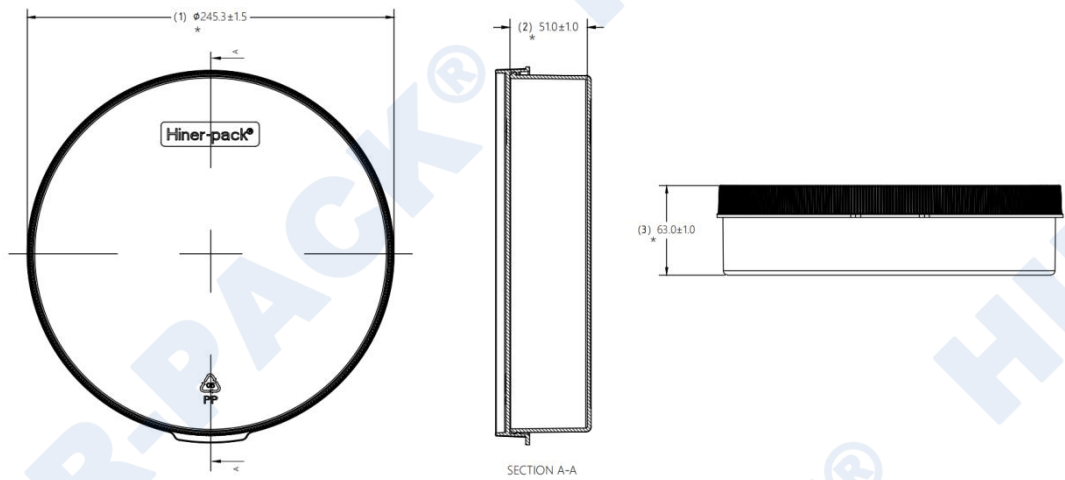
## SPECIFICATIONS

- 245.3 mm L × 245.3 mm W × 63 mm H (9.66" × 9.66" × 2.48")
- Maximum load capacity is 25 pieces
- Sold in full case quantity (32)

## FEATURES & BENEFITS

- Interleaf separators prevent direct wafer surface contact
- Foam liners and cushion disks absorb shocks and vibration
- The bottom and the top cover are designed to facilitate the operator to open and ensure safety during transportation

DIMENSION



BASIC INFORMATION

Part Number	Collocation Reference	Wafer Size
MHWJ-8/25-230/50-WH	Bottom+Foam+Interleaf+Liner+Top	200 mm

REFERENCE ILLUSTRATION



The above illustration is for reference only. Please refer to the actual product for accuracy.

## TECHNICAL DATA

PROPERTY	TEST METHOD	RATED VALUES
Density	ISO 1183	0.9 g/cm <sup>3</sup>
Melt Index	ISO 1133	15 g/10min
Melting Point	DSC	146°C
Distortion Temperature	ISO 75	95°C
Vicat softening temperature	ISO 306	125°C
Tensile Strength at Yield	ISO 527	280 kg/m <sup>2</sup>
Tensile Elongation at Break	ISO 527	300 %
Rockwell hardness R scale	ISO 2039	98
Tensile Strain at Break	ISO 527-2 (50mm/min)	10 %
Flexural Modulus	ISO 178	10500 kg/m <sup>2</sup>
Flow Shrinkage	FPC Method	1.3~1.7 %
LZOD Impact Strength	ISO 180 23°C	6 kg.cm/cm
	-20°C	--- notch

The information on technical data included in this document is based on our experience to date, and we believe it to be reliable. Data is obtained from specimens molded under controlled conditions from representative samples of the compound described. Properties may be affected by the molding techniques and by the size and shape of the item molded. We cannot guarantee favorable results and no assurances can be implied that all molded articles have the sample properties as those listed.



Hiner-pack®

### Corporate Headquarters

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### Customer Service

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